

COMBINED DECLARATION AND POWER OF ATTORNEY FOR UTILITY PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention titled:

Semiconductor multi-package module having package stacked over ball grid array package and having wire bond interconnect between stacked packages

tne spe	ecification of which				
	is attached hereto.				
	was filed on August 2, 2003 as Application No. 10/632,568,				
	and was amen	ded on (<i>if applicable</i>).			
specific		I have reviewed and unners, as amended by any a			ve-identified
"Each i good fa that ind known patenta	tion in accordance with andividual associated wit aith in dealing with the Clividual to be material to to be material to	ty to disclose information of the filing and prosecution of the filing as defined in the filing as defined in a patent was cited by the filing and the filing are filled.	Regulations, § 1.56(a) on of a patent application of a patent application to disclose to the Office this sectionThe dustails all informat	which states in ron has a duty of fice all informatity to disclose all information known to be	elevant part: f candor and ion known to I information e material to
foreign	tion(s) for patent or inv	priority benefits under T ventor's certificate as ind r inventor's certificate on t claimed:	icated below and hav	e also identified	d below any
	Prior Foreign Application	on(s)		Priority Claimed	
				☐ Yes	□ No
	(Number) (Country)	(Day/Month/Year Filed)		_	
	(Number) (Country)	(Day/Manth/Voor Filad)		☐ Yes	☐ No
	(Number) (Country)	(Day/Month/ Year Filed)			
applica disclose United Code o	tion(s), and under Titl tion(s), listed below and ed in the prior United S States Code, § 112, I a of Federal Regulations, §	enefit under Title 35, Ur e 35, United States Co , insofar as the subject m tates application in the necknowledge the duty to co 1.56(a) which occurred al filing date of this application.	de, § 119(e) of any atter of each of the clananner provided by the disclose material information between the filing date.	United States sims of this appli e first paragraph nation as defined	provisional ication is not n of Title 35, d in Title 37,
	60/411,590	17 September 2002	Pending		
٠	(Application No.)	Filing Date)	(Status: Patented, P	ending, Abando	ned)
	(Application No.) (Filing Date) (Status: Patented, Pending, Abandoned)				
	(Application No.)	(Filing Date)	(Status: Patented, P	ending, Abando	ned)

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith, and to file, prosecute and to transact all business in connection with international applications directed to said invention:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18, United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.